



PARTNERSHIP FOR ADVANCED COMPUTING IN EUROPE

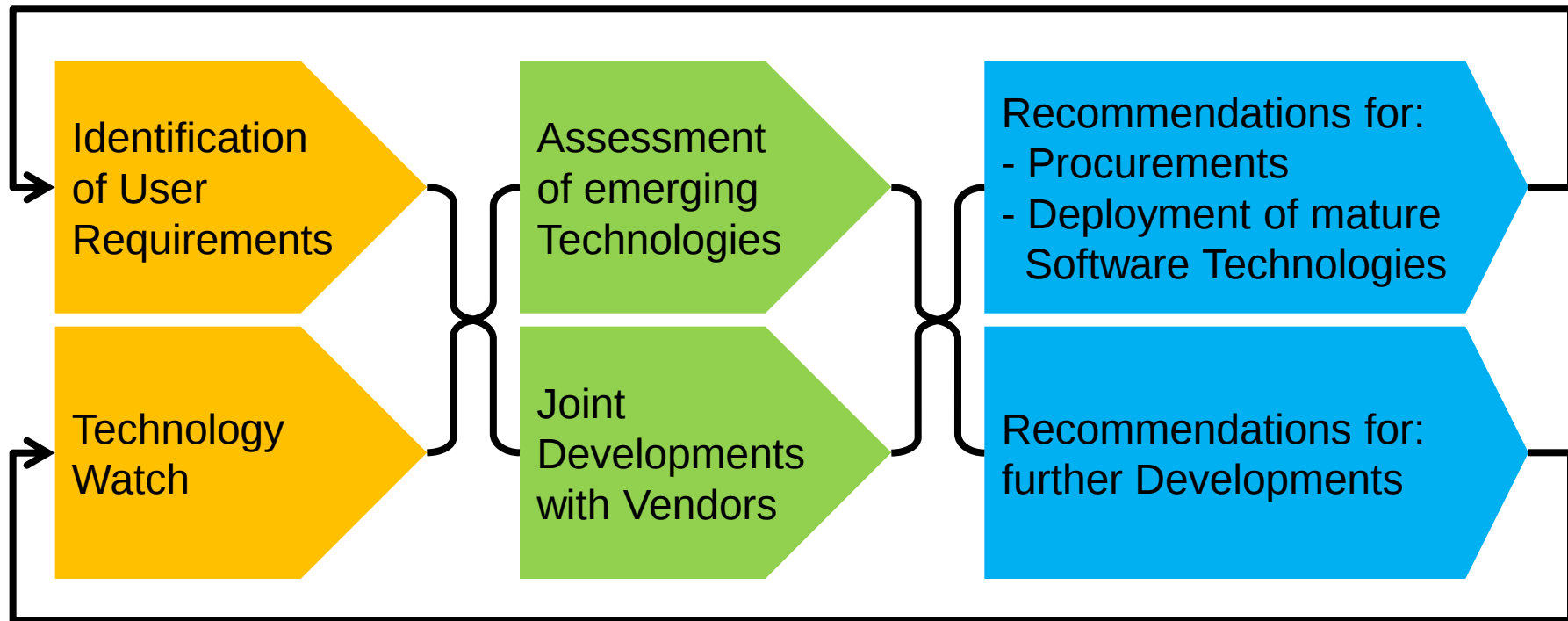
Prototyping in PRACE 5. PRACE Executive Industrial Seminar

Torsten Wilde (LRZ), 1IP-WP9 & 2IP-WP11 Leader, Bad Boll, Apr-2013

Outline

- Prototyping in PRACE
- WP Objectives
- Results
 - T9.1 Technology Watch and Assessment
 - T9.2 Multi-Petascale Software Environment
 - T9.3 Future Highly energy efficient Tier-0 systems
- Conclusions

Prototyping is Mandatory for PRACE



Objectives of WP9

- Assessment of emerging hardware and software technologies for multi-Petascale systems (T9.1)
- Evaluation of future system software, programming paradigms and tools (T9.2)
- Evaluation of energy efficient HPC solutions (T9.3)
- http://www.prace-ri.eu/Public-Deliverables?lang=en#PD_1IP

T9.1 TECHNOLOGY WATCH AND ASSESSMENT

Agenda for PRACE workshop, Daresbury Laboratory, 5 & 6 April 2011

Tuesday 5 April 14:00-14:15	Welcome and introductions
14:15-15:00	T-platforms Andrey Slepukhin, Keith Corless, Gilbert Lauber, Igor Zacharov Extoll interconnect design
15:00-15:15	Break - tea/coffee
15:15-16:00	Bull Jean-Pierre Panziera Bull's technology vision especially related to "interconnect" and "processing units"
16:00-16:45	IBM Andy Grant, Ian Green, Crispin Keable High temperature water cooling
Wednesday 6 April 09:30-10:15	SGI Simon Appleby, Michael Woodacre
10:15-11:00	Xyratex Ian Roberts
11:00-11:15	Break - tea/coffee
11:15-12:00	nVIDIA Tim Lanfear
12:00-13:00	Lunch in canteen
13:00-13:45	Convey Gerald Sommariva
13:45-14:30	ARM-Xilinx Jeff Underhill • 1 ARM&Xilinx offering Requirements gathering from audience
14:30-14:45	Break - tea/coffee
14:45-15:30	Texas Instruments Arnon Friedmann, Pekka Varis Texas Instruments high performance computing infrastructure vision for 2012 and beyond; Leveraging low power consumption multicore system-on-chips targeting dense compute blade architecture
15:30-16:15	DDN Glenn Wright, Peter Green DDN strategy for hardware and software & storage for research data
16:15-17:00	Mellanox Colin Bridger

Exascale Technology Assessment Results D9.1.2

1. Data and memory hierarchy – 3D stacking of memory, silicon photonics, deepening memory hierarchies
2. Fault tolerance – possible, at a price of increased hardware and running cost
3. Energy efficiency – the need for software optimisation
4. Architecture – heterogeneity, type of cores, interconnect
5. Scale – number of cores and massive parallelism

Consequence of future hardware technologies on software,
assessment of programming languages and the system software

T9.2 MULTI-PETASCALE SOFTWARE ENVIRONMENT

Final Software Evaluation Report (D9.2.2)

- Three main aspects
 - *Programming Languages*
for CPUs, GPUs and hybrid use.
 - *System Software*
system and data management tools, MPI and other communication libraries and resource management.
 - *Computer Architectures*
Recommendations and lessons learned from the prototype owners.

Programming Languages for hybrid programming

- pragma-based: OpenACC / OmpSs
 - Boost productivity, not ready for production level software
 - `#pragma acc kernels copyin(temp_in[0:ni*nj])`
`copy(temp_out[0:ni*nj])`
- OpenCL / CUDA:
 - OpenCL closed performance gap but is lacking support for latest hardware features
- UPC (Unified Parallel C):
 - low level knowledge is required in order to write performant code

Tools

- Tools for hybrid CPU/GPU systems
 - Support hybrid application debugging
 - Memory tracing
 - Profiling
- I/O tools
 - I/O will be bottleneck at Exascale, need profiling tools for I/O operations
- Usability of future tools
 - Exponential increase of available information at Exascale requires a re-thinking of data presentation
 - Filtering traces from millions of running threads
 - Representing results

Energy benchmark, prototype assessment and status

T9.3 FUTURE HIGHLY ENERGY EFFICIENT TIER-0 SYSTEMS

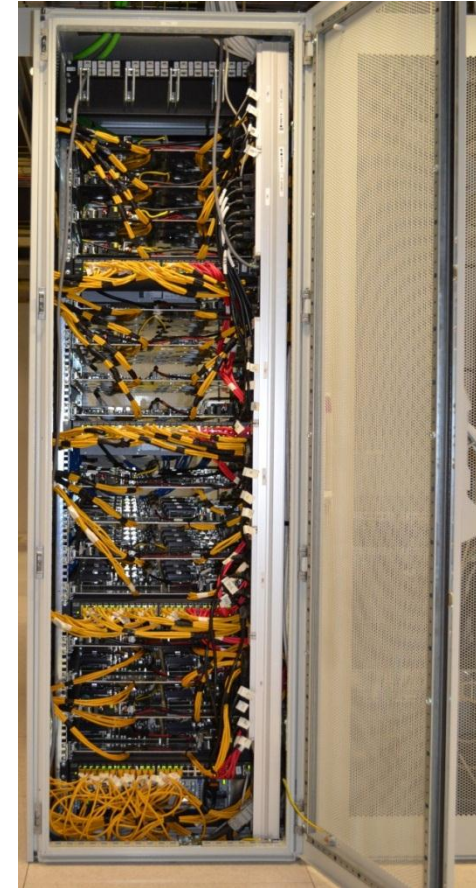
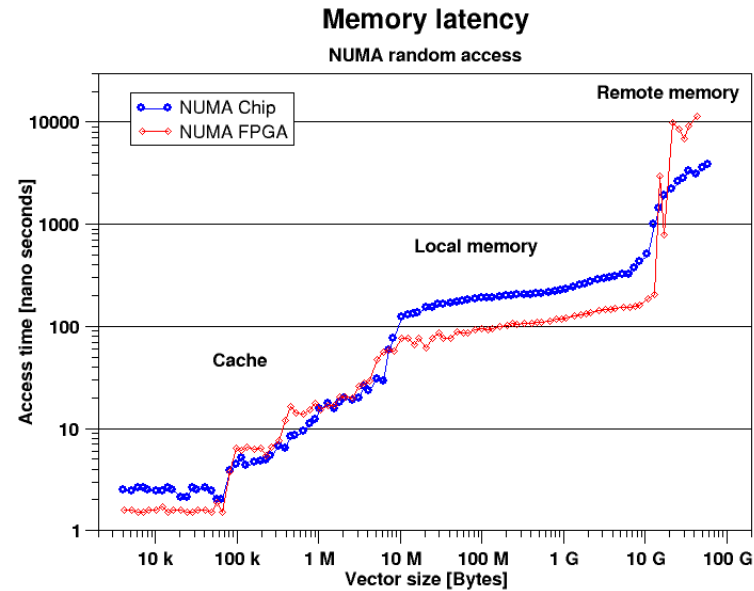
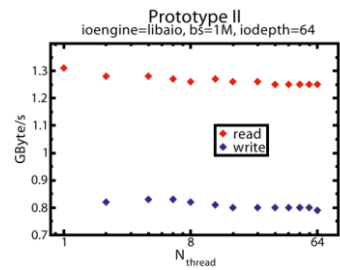
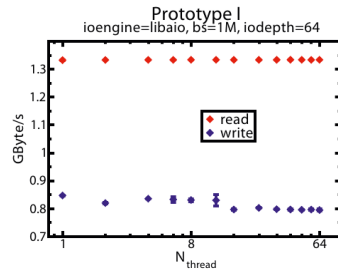
1st Set of Prototypes

- Memory and I/O
 - Exascale I/O and MPP I/O Prototypes up and running
 - Working on common benchmarks
 - NUMA-CIC
 - 1st phase running, waiting for final NUMA hardware revision
- Energy To Solution
 - ARM, LRZ – Hot Water Cooled and SNIC-DSP Prototypes up and running
 - Writing final reports till end of October
- Accelerators:
 - GPGPU and Hybrid CPU/GPU up and running
 - GPGPU will provide final report by end of September
 - CPU/GPU is evaluating the 2nd phase hardware



Neo 3000 Xyratex
prototype at CEA





1ST SET OF PROTOTYPES RESULTS



Node technologies

- optimized implementation of matrix-multiplication
 - FPGA: 5 – 10 times higher energy efficiency than an x86 software solution
 - DSP: 2 – 5 times
 - Programming effort very high
- First and second generation x86+GPU APUs
 - not competitive in regards to energy efficiency
 - Benchmarking behavior similar to GPUs
- A HPC cluster can be build with mobile SoC (ARM)
 - floating-point capabilities of the current generation mobile CPUs is insufficient to be competitive in terms of energy efficiency

I/O

- tighter integration of I/O and file systems into MPP and cluster systems and the use of flash technology is beneficial
- The concept of using flash and disks in a tiered file system is working in GPFS.
- Good performance depends on good software implementations
- There are efficiency and scalability issues related to large file systems in which a large fraction of the files are small.

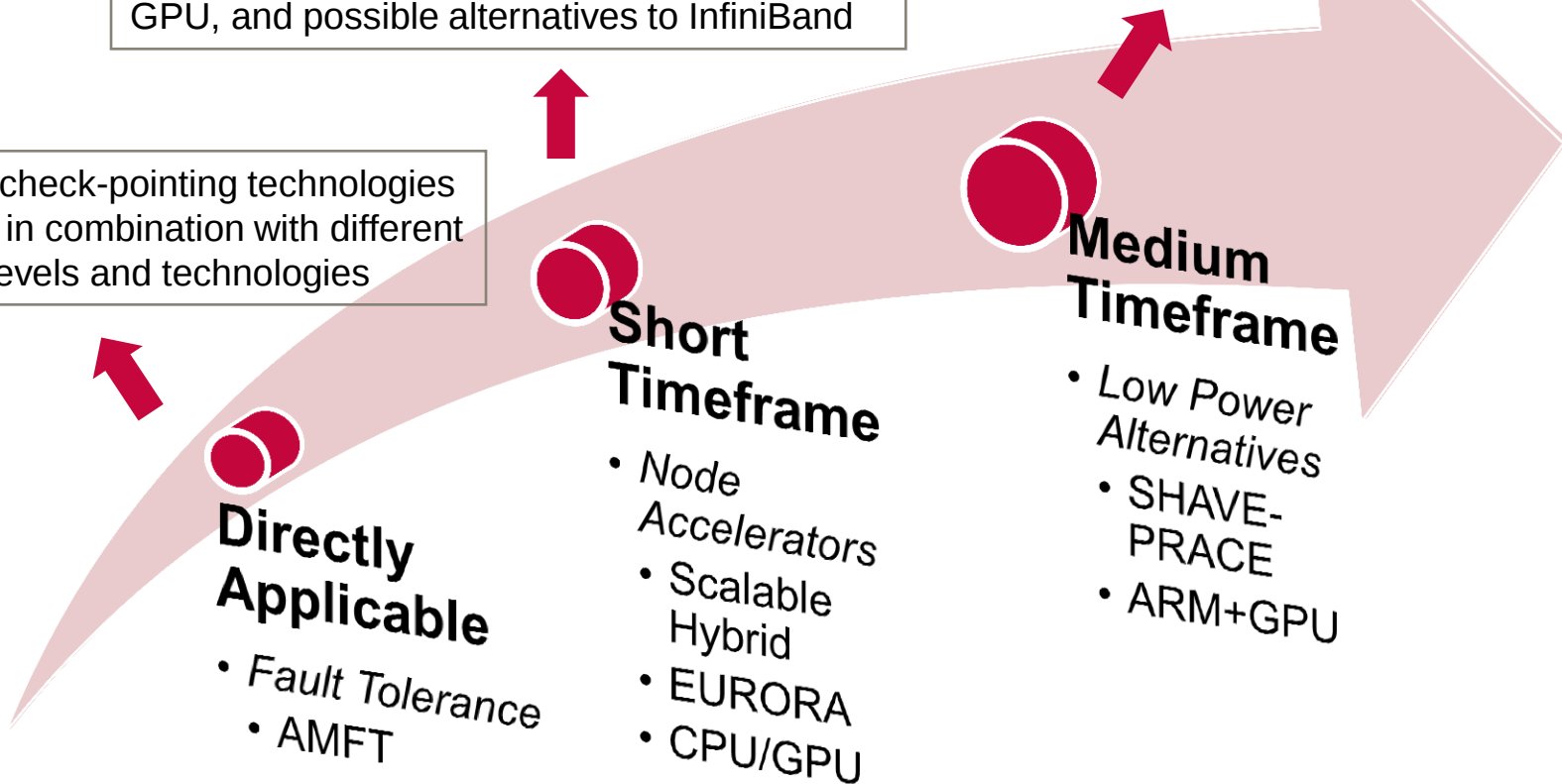
Benchmarking results

- direct relationship between performance and energy efficiency for most benchmarks
 - Software optimization most important
- highest performing hardware platform does not, in general, minimize the energy consumption for a task
- Direct hot water cooling is viable
 - Re-use via adsorption possible

Evaluate the usefulness and usability of each current accelerator technology, e.g. Intel Many Integrated Cores (MIC), Nvidia GPU and AMD GPU, and possible alternatives to InfiniBand

evaluate possible low-power alternatives to current HPC systems based on Systems on Chip (SoC) solutions.

Evaluate new check-pointing technologies (FTI and MFT) in combination with different storage levels and technologies



Directly Applicable

- *Fault Tolerance*
- AMFT

Short Timeframe

- Node Accelerators
- Scalable Hybrid
- EURORA
- CPU/GPU

Medium Timeframe

- Low Power Alternatives
- SHAVE-PRACE
- ARM+GPU

Conclusion

- Future technology:
 - Flash based I/O devices
 - Warm water cooling
 - Prove of concept, low-power commodity parts can be used for HPC
- New technologies are important for PRACE
- Results guide development of PRACE-RI